

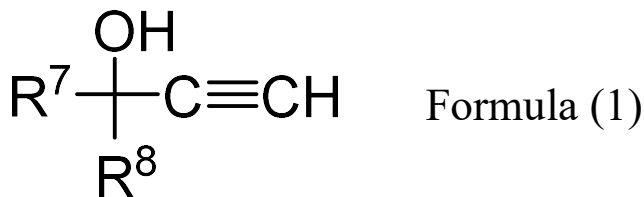
ABSTRACT

POLYSILOXANE-CONTAINING TEMPORARY ADHESIVE COMPRISING
HEAT-RESISTANT POLYMERIZATION INHIBITOR

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There is provided a temporary adhesive without the formation of voids between a support and a wafer.

A temporary adhesive for separatably attaching a support to a circuit side of a wafer to process a rear surface of the wafer, the temporary adhesive comprising a component (A) that is cured by a hydrosilylation reaction; a polymerization inhibitor (B) having a 5% mass decrease temperature of 80°C or higher as measured using a Tg-DTA; and a solvent (C). The component (A) may comprise a polysiloxane (A1) including a polyorganosiloxane (a1) containing a C₁₋₁₀ alkyl group and a C₂₋₁₀ alkenyl group, and a polyorganosiloxane (a2) containing a C₁₋₁₀ alkyl group and a hydrogen atom; and a platinum group metal-based catalyst (A2). The polymerization inhibitor (B) may be a compound of formula (1):



(wherein R⁷ and R⁸ are each a C₆₋₄₀ aryl group, or a combination of a C₁₋₁₀ alkyl group and a C₆₋₄₀ aryl group).

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[No figure]